



Material Content Data Sheet



Sales Product Name	BTS117	Issued	03. May 2021
MA#	MA001017900		
Package	PG-TO220-3-1	Weight*	2019.34 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	2.906	0.14	0.14	1439	1439
chip_2	inorganic material	silicon	7440-21-3	0.454	0.02	0.02	225	225
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		121	
	non noble metal	iron	7439-89-6	0.816	0.04		404	
	non noble metal	copper	7440-50-8	815.335	40.40	40.45	403763	404288
wire	non noble metal	aluminium	7429-90-5	1.802	0.09	0.09	893	893
encapsulation	organic material	carbon black	1333-86-4	6.412	0.32		3175	
	inorganic material	antimonytrioxide	1309-64-4	13.407	0.66		6639	
	plastics	brominated resin	-	15.156	0.75		7505	
	plastics	epoxy resin	-	110.754	5.48		54846	
	inorganic material	silicondioxide	60676-86-0	437.185	21.65	28.86	216499	288664
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10628	10628
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	121	122
solder	non noble metal	tin	7440-31-5	0.055			27	
	noble metal	silver	7440-22-4	0.069			34	
	non noble metal	lead	7439-92-1	2.649	0.13	0.13	1312	1373
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	78	78
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		88	
	non noble metal	iron	7439-89-6	0.590	0.03		292	
	non noble metal	copper	7440-50-8	589.466	29.19	29.23	291910	292290
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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